

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number				
Nexperia B.V.		PMEG3010ER-Q				
Name of Laboratory		Part Description				
Assembly reliability labs		Nexperia DHAM Schottky SMD package				
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects
TEST Pre- and Post-Stress Electrical Test		Tamb = 25 °C	N/A	see below	all parts	see below
# E1						
# A1	PC Preconditioning	JESD22-A113				
		Bake Tamb = 125 °C	24 hours			
		Soak Tamb = 85 °C, RH = 85%	168 hours			
# B1	HTRB High Temperature Reverse Bias	MIL-STD-750-1				
		M1038 Method A				
		Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage ^[1]	1000 hours	206	9320	0
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0
# A3 or	UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	96 hours	311	14080	0
# A3 alt	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)				
# A2 alt	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^{[1], [2]}	1000 hours	311	14080	0
# A5	IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	312	14120	0
# C8	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	269	8070	0
# C10	SD Solderability	J-STD-002		222	6660	0

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9320	0	0,46	2,19E+09